

HSD88

Silicon Schottky Barrier Diode for Detector, Mixer

REJ03G0602-0100 (Previous: ADE-208-1386) Rev.1.00 Apr 26, 2005

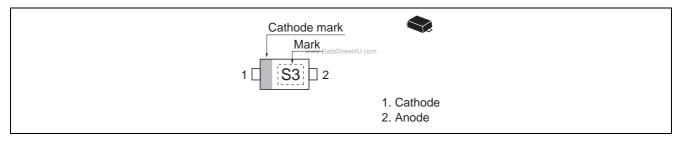
Features

- Low capacitance. (C = 0.8 pF max)
- Low forward voltage.
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Cathode Mark	Package Name	Package Code (Previous Code)
HSD88	S3	SFP	PUSF0002ZB-A (SFP)

Pin Arrangement





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
ltem	Symbol	Value	Unit
Reverse voltage	V _R	10	V
Average rectified current	lo	15	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–55 to +125	٥C

Electrical Characteristics

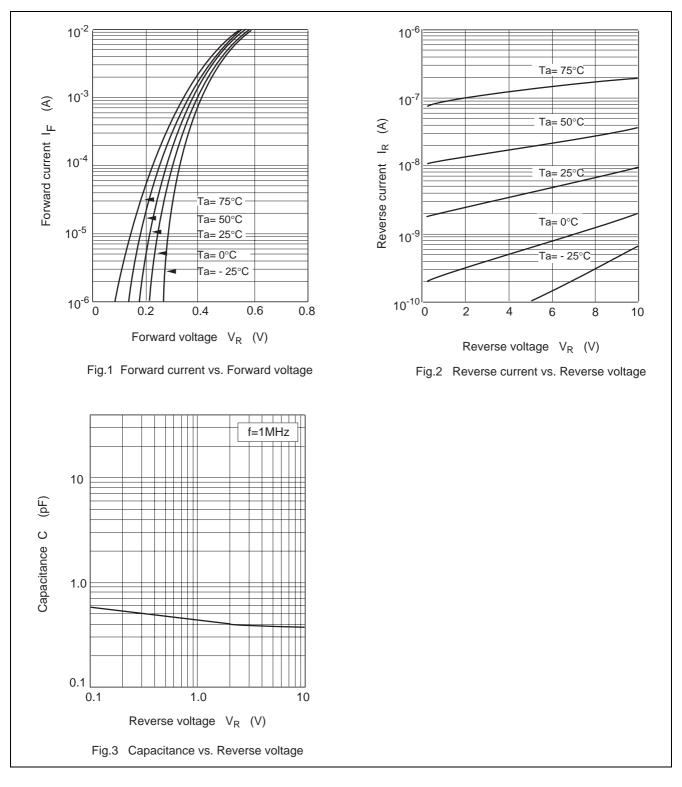
						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _{F1}	0.350	—	0.420	V	I _F = 1 mA
	V _{F2}	0.500	—	0.580		I _F = 10 mA
Reverse current	I _{R1}	_	_	0.2	μA	V _R = 2 V
	I _{R2}	_	—	10		V _R = 10 V
Capacitance	С	_	—	0.80	pF	V _R = 0 V, f = 1 MHz
ESD-Capability *1	—	30	_	_	Ω	C = 200 pF, Both forward and
						reverse direction 1 pulse.

Notes: 1. Failure criterion ; $I_R > 0.4~\mu\text{A}$ at V_R = 2 V

2. Please do not use the soldering iron due to avoid high stress to the SFP package.

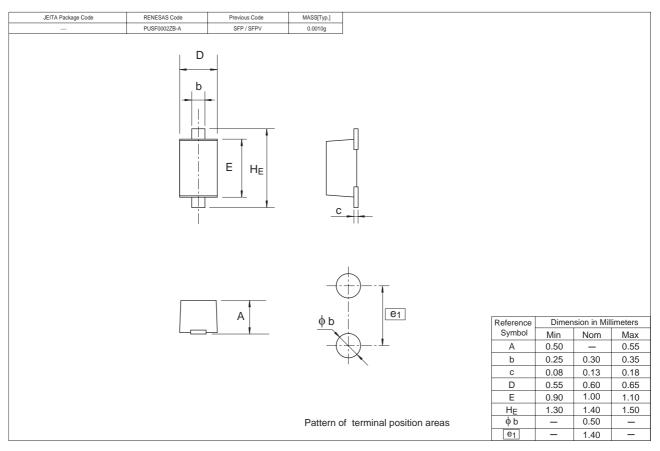


Main Characteristic





Package Dimensions





Renesas Technology Corp. Sales Strategic Planning Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

Keep safety first in your circuit designs! 1. Renesas Technology Corp. puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

Notes regarding these materials

- Notes regarding these materials
 1. These materials are intended as a reference to assist our customers in the selection of the Renesas Technology Corp. product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Renesas Technology Corp. or a third party.
 2. Renesas Technology Corp. assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms, or circuit application examples contained in these materials.
 3. All information contained in these materials, including product data, diagrams, charts, programs and algorithms represents information on products at the time of publication of these materials, and are subject to change by Renesas Technology Corp. without notice due to product improvements or other reasons. It is therefore recommended that customers contact Renesas Technology Corp. or an authorized Renesas Technology Corp. product distributor for the latest product information before purchasing a product listed herein.
 The information before purchasing a product listed herein.
 The information described here may contain technical inaccuracies or typographical errors.
 Renesas Technology Corp. assumes no responsibility for any damage, ilability, or other loss rising from these inaccuracies or errors.
 Please also pay attention to information published by Renesas Technology Corp. by various means, including the Renesas Technology Corp. Semiconductor home page (http://www.renesas.com).
 When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information actal system before making a final decision on the applicability of the information and products. Renesas Technology Corp. assumes no responsibility for any damage or manufa

- use. 6. The prior written approval of Renesas Technology Corp. is necessary to reprint or reproduce in whole or in part these materials. 7. If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination. Any diversion or reexport contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited. 8. Please contact Renesas Technology Corp. for further details on these materials or the products contained therein.



RENESAS SALES OFFICES

Refer to "http://www.renesas.com/en/network" for the latest and detailed information.

Renesas Technology America, Inc. 450 Holger Way, San Jose, CA 95134-1368, U.S.A Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K. Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology Hong Kong Ltd. 7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd. 10th Floor, No.99, Fushing North Road, Taipei, Taiwan Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology (Shanghai) Co., Ltd. Unit2607 Ruijing Building, No.205 Maoming Road (S), Shanghai 200020, China Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

Renesas Technology Singapore Pte. Ltd. 1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632 Tel: <65> 6213-0200, Fax: <65> 6278-8001

http://www.renesas.com